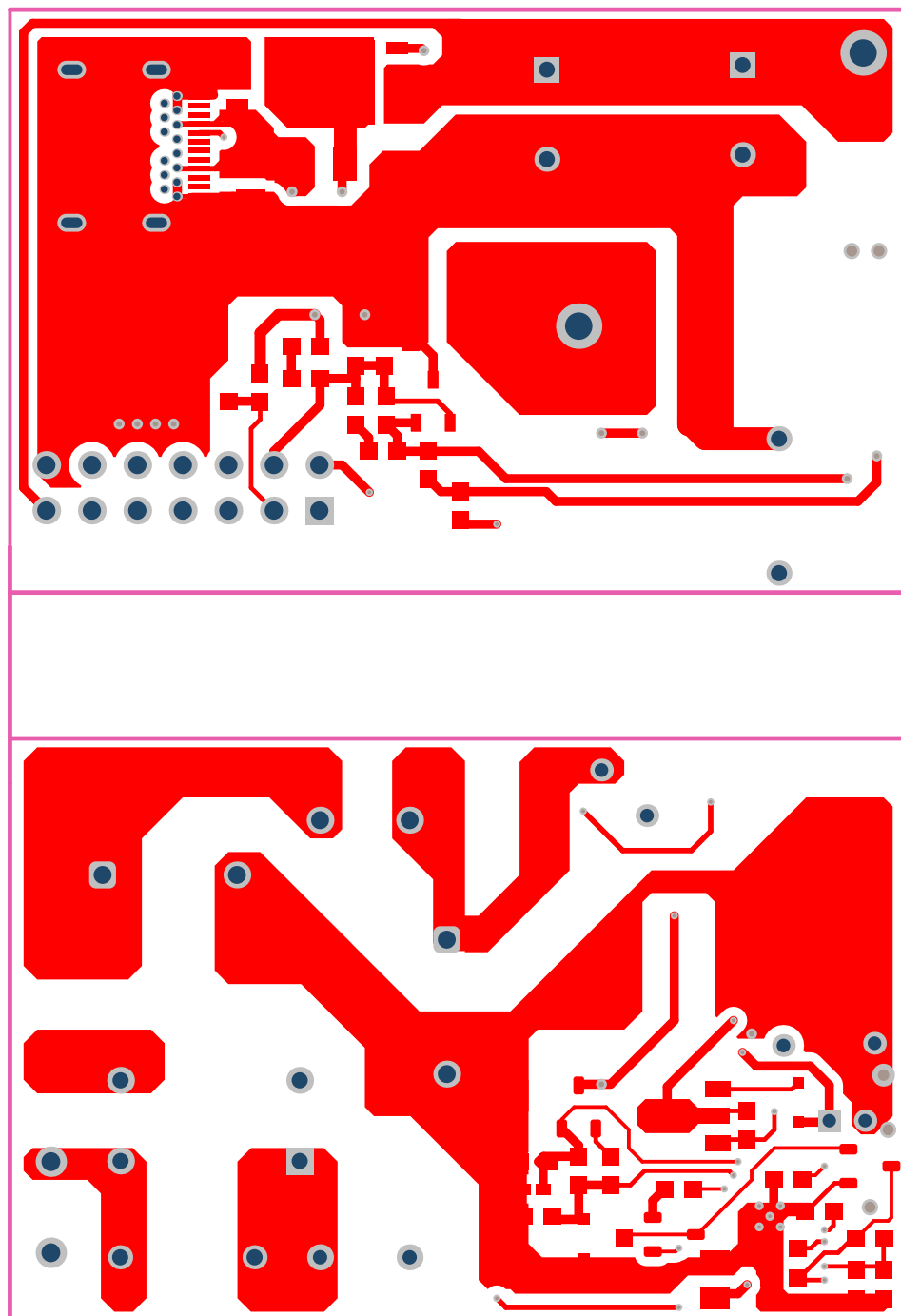


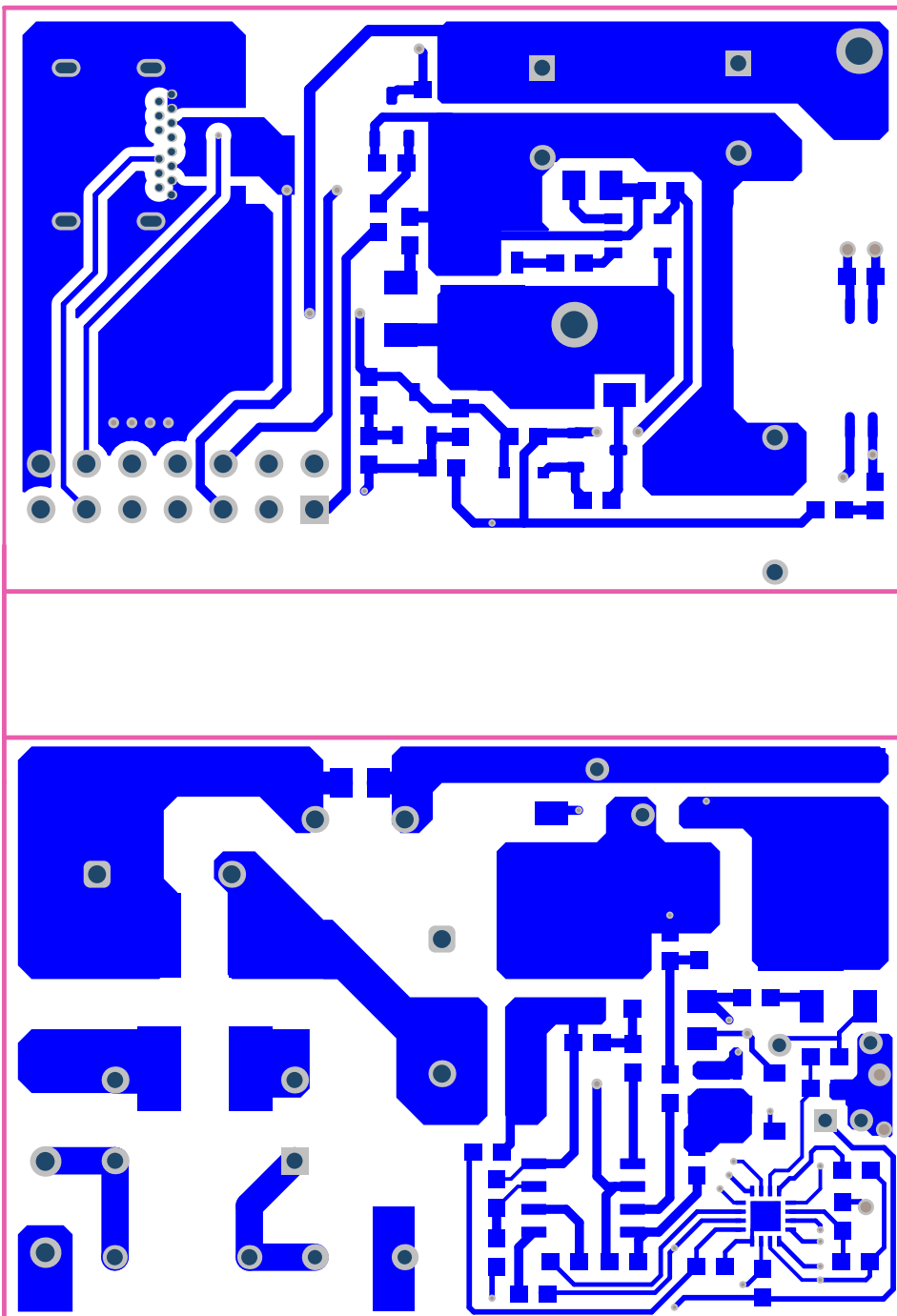




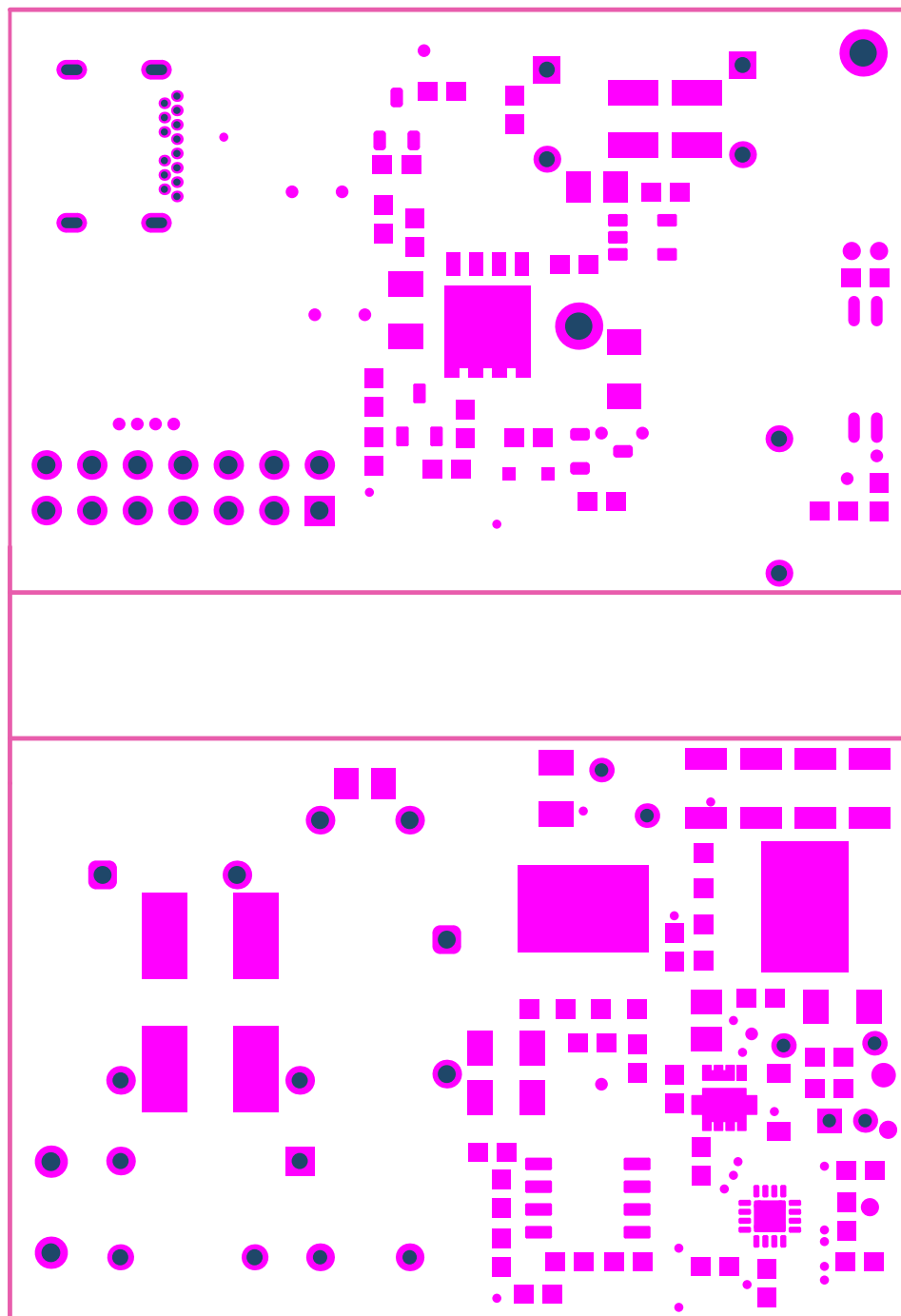
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: N/A		
PLOT NAME = Top Solder Mask	GENERATED : 12/8/2017 3:53:32 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: N/A		
PLOT NAME = Top Layer	GENERATED : 12/8/2017	3:53:33 PM	TEXAS INSTRUMENTS

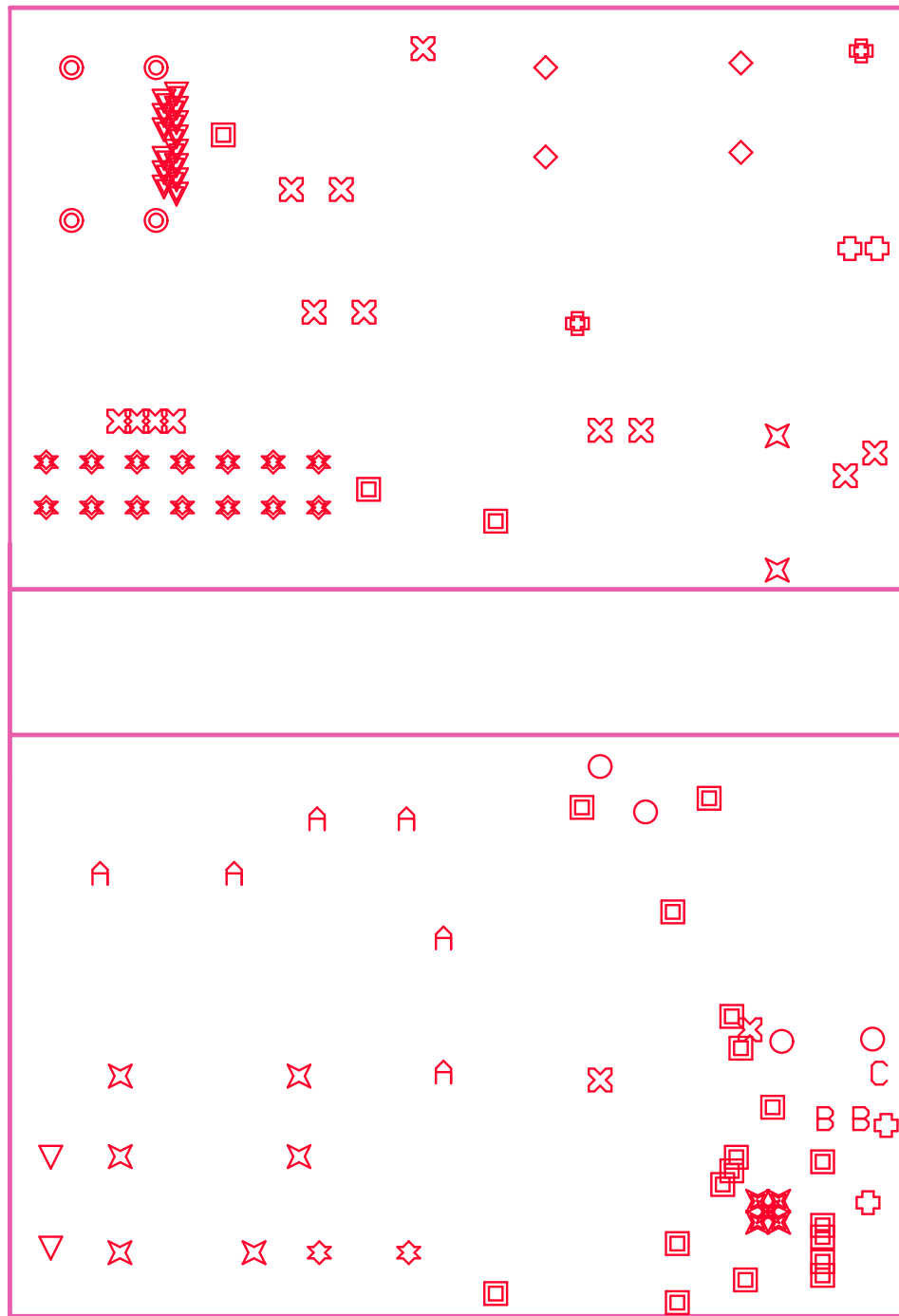


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: N/A		
PLOT NAME = Bottom Layer	GENERATED : 12/8/2017 3:53:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: N/A		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/8/2017	3:53:35 PM	TEXAS INSTRUMENTS

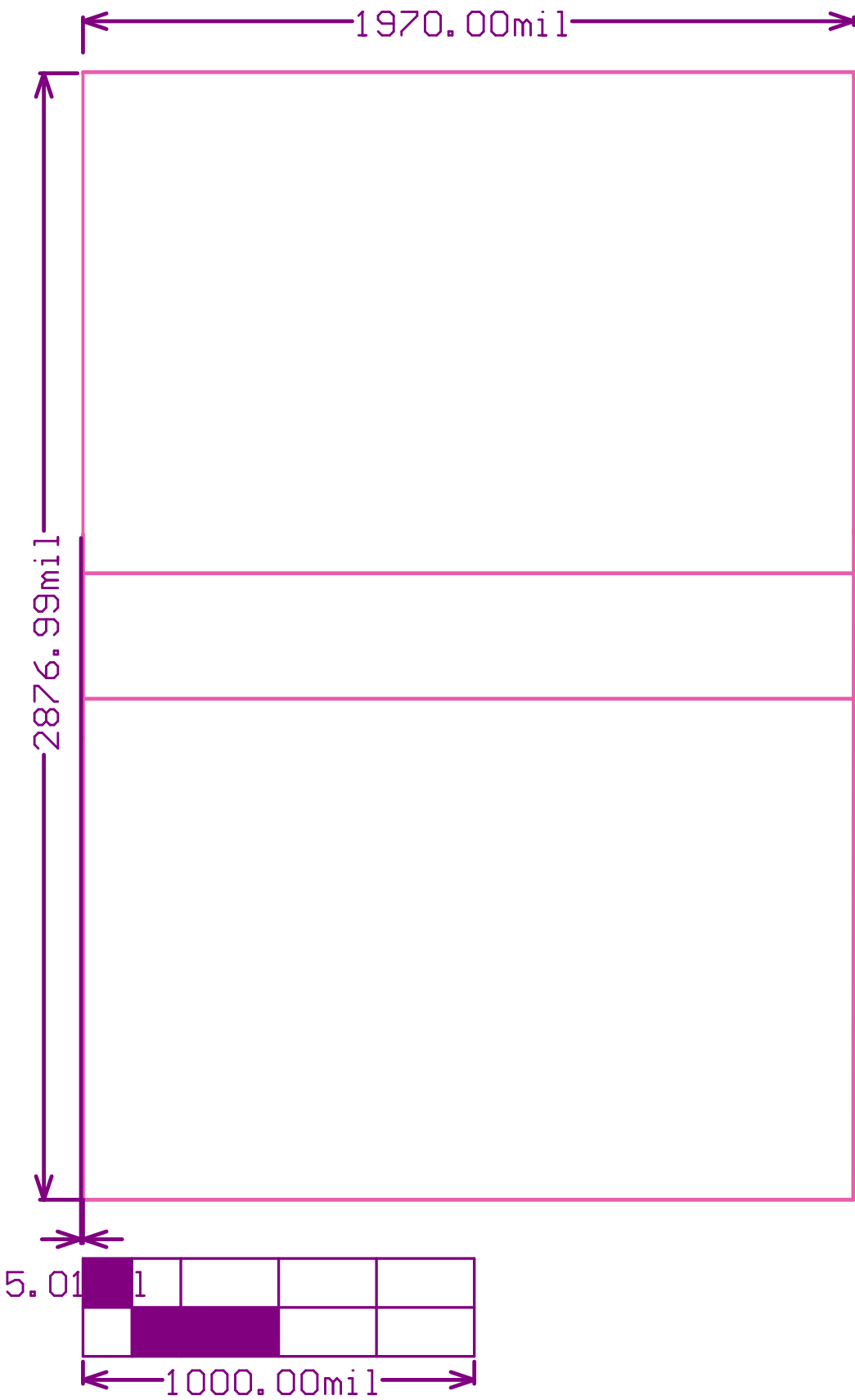




Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
✕	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
◻	21	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
✕	15	12.00mil (0.305mm)	PTH	Round	Top Layer - Bottom Layer	
▽	14	15.75mil (0.400mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	4	24.00mil (0.610mm)	PTH	Round	Top Layer - Bottom Layer	
C	1	25.00mil (0.635mm)	PTH	Round	Top Layer - Bottom Layer	
B	2	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
○	4	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	2	31.50mil (0.800mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	35.00mil (0.889mm)	PTH	Round	Top Layer - Bottom Layer	
✕	8	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⋈	6	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
⊛	14	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	
▽	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
⊕	2	60.00mil (1.524mm)	PTH	Round	Top Layer - Bottom Layer	
⊙	4	23.62mil (0.600mm)	PTH	Slot	Top Layer - Bottom Layer	
	108 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: N/A		
PLOT NAME = Drill Drawing	GENERATED : 12/8/2017	3:53:37 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP40328	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: N/A		
PLOT NAME = Board Dimensions	GENERATED : 12/8/2017	3:53:38 PM	TEXAS INSTRUMENTS



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